

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Harumoto KIMURA	05/18/2007
Kazunari HANAOKA	05/28/2007
Yousuke OYAMA	05/31/2007
Riichi NAKANO	05/30/2007

RECEIVING PARTY DATA

Name:	MATSUI MFG. CO. LTD.
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Postal Code:	542-0012

Name:	KABUSHIKI KAISHA MEIKI SEISAKUSHO
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11721546

CORRESPONDENCE DATA

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OP \$40.00 11721546

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NAME OF SUBMITTER: Mark D. Saralino

Total Attachments: 2
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ASSIGNMENT

WHEREAS:

NAME(S) AND ADDRESS(ES) OF INVENTOR(S)

Harumoto KIMURA
c/o MATSUI MFG. CO., LTD., Osaka Kojo, 2-19,
Shodaitajika, Hirakata-shi, Osaka 573-1132
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~~Yousuke OYAMA~~
~~Hironori KOYAMA~~ *Y.O. 2007.5.31*
c/o KABUSHIKI KAISHA MEIKI SEISAKUSHO, 2,
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~~Riichi NAKANO~~
~~Toshikazu NAKANO~~ *R.N. 2007.5.30*
c/o KABUSHIKI KAISHA MEIKI SEISAKUSHO, 2,
Ohne, Kitasaki-cho, Ohbu-shi, Aichi 474-8666
Japan

(hereinafter referred to as ASSIGNOR), have invented a certain invention entitled:

TITLE OF INVENTION

FILLING METHOD AND FILLING APPARATUS OF POWDER-PARTICLE MATERIAL IN COMPRESSION MOLDING

for which application for Letters Patent of the United States has been:

PARTICULARS OF APPLICATION

executed concurrently herewith,
 filed under U.S. Application No. 11/721,546 on 13 June 2007, or
 filed under Express Mail Label No. _____ on _____.

WHEREAS:

NAME, STATE OF INCORPORATION AND ADDRESS OF ASSIGNEE

MATSUI MFG. CO., LTD.
5-26, Tanimachi 6-chome, Chuo-ku, Osaka-shi, Osaka 542-0012 Japan

KABUSHIKI KAISHA MEIKI SEISAKUSHO
2, Ohne, Kitasaki-cho, Ohbu-shi, Aichi 474-8666 Japan

(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention (including all inventions should said application be deemed to include multiple inventions).

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR(S) of the sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest to said invention and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms for which the same may be granted.

ASSIGNOR hereby covenants that ASSIGNOR has the full power to make this assignment and that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and that ASSIGNOR will testify as to the same in any legal proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce patent protection for said invention in all countries.

I authorize the patent attorney of record and/or having power of attorney in the U.S. patent application identified above to insert the serial number and filing date information for the patent application in the appropriate spaces in this assignment document when that information becomes available.

FULL NAME(S) OF INVENTOR(S)

Date May 18, 2007 Harumoto Kimura
(Harumoto KIMURA)

Date May 28, 2007 Kazunari Hanaoka
(Kazunari HANAOKA)

Date May 31, 2007 Yousuke Oyama
(~~Hironori KOYAMA~~) Y.O. 2007.5.31
Yousuke OYAMA

Date May 30, 2007 Riichi Nakano
(~~Foshikazu NAKANO~~) R.N. 2007.5.30
Riichi NAKANO

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